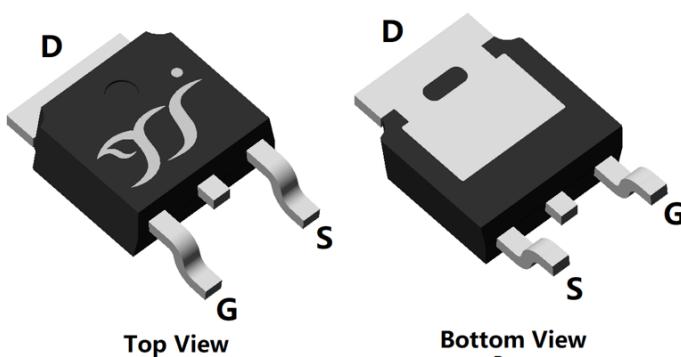
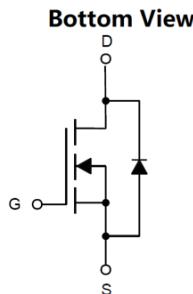


**N-Channel Enhancement Mode Field Effect Transistor****TO-252****Product Summary**

- V_{DS} 30V
- I_D 80A
- $R_{DS(ON)}$ (at $V_{GS} = 10V$) <4.9mohm
- $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) <7.0mohm
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- High current load applications
- Load switch
- Hard switched and high frequency circuits
- Uninterruptible power supply

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	30	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_c=25^\circ\text{C}$	I_D	80	A
	$T_c=100^\circ\text{C}$		50	
Pulsed Drain Current ^A		I_{DM}	190	A
Single Pulse Avalanche Energy ^B		E_{AS}	100	mJ
Total Power Dissipation ^C	$T_c=25^\circ\text{C}$	P_D	38	W
	$T_c=100^\circ\text{C}$		15	W
Thermal Resistance Junction-to-Ambient ^D		$R_{\theta JA}$	60	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	3.3	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	°C

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJD80N03B	F1/F2	YJD80N03B	2500	/	25000	13" reel

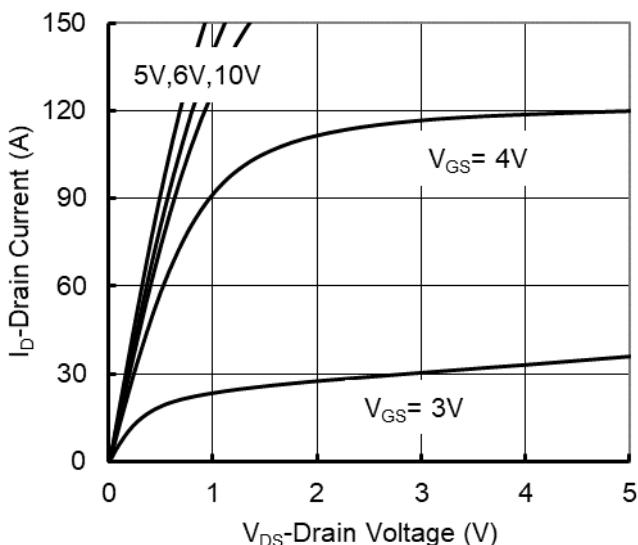
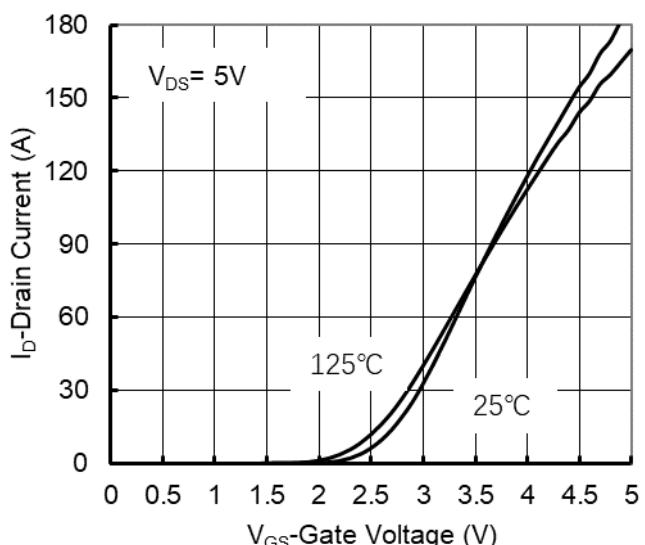
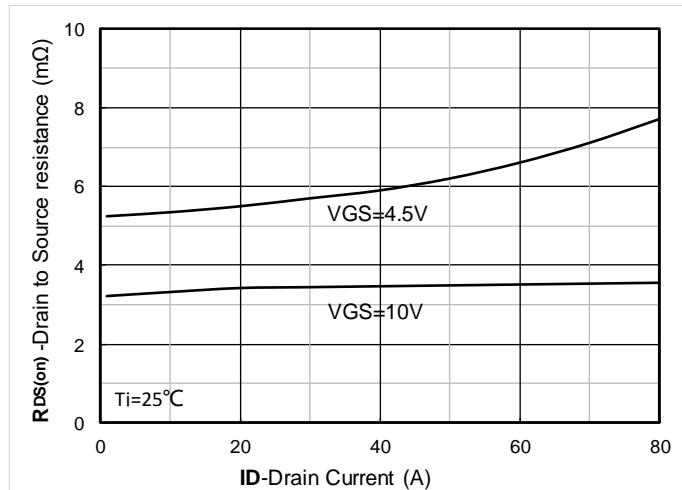
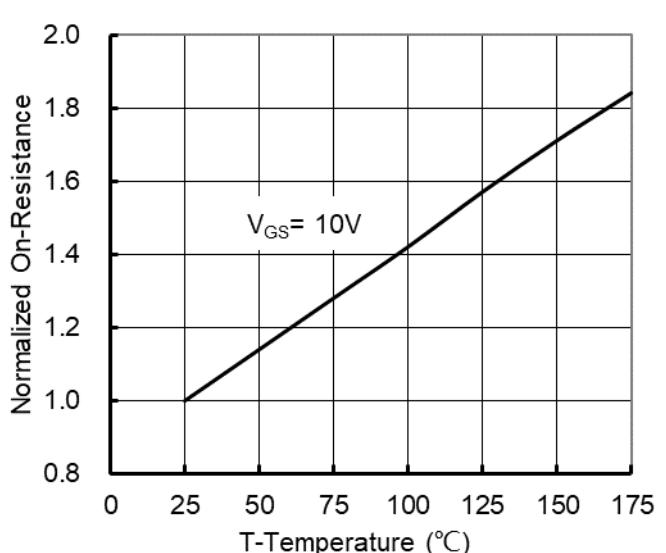
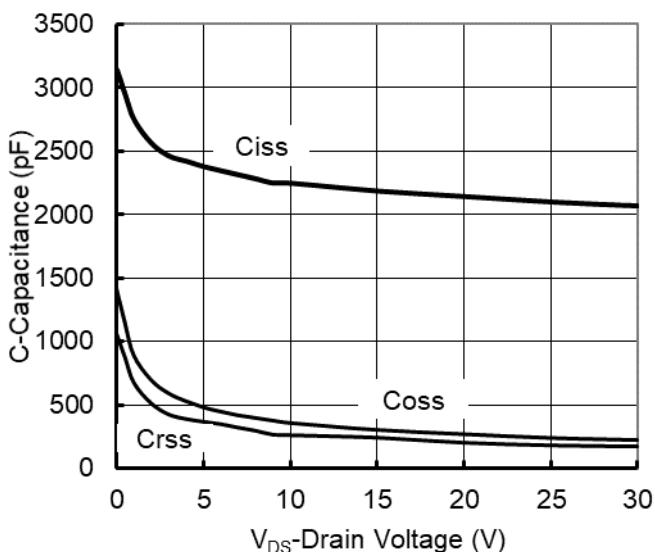
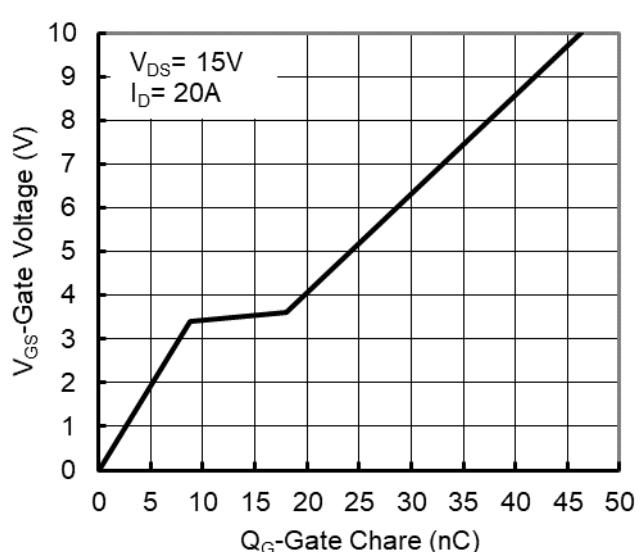


YJD80N03B

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	1	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 20\text{A}$		3.4	4.9	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 15\text{A}$		5.4	7.0	
Diode Forward Voltage	V_{SD}	$I_{\text{S}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$		0.85	1.2	V
Gate resistance	R_{G}	f=1MHz, Open drain	-	2.7	-	Ω
Maximum Body-Diode Continuous Current	I_{S}				80	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2191		pF
Output Capacitance	C_{oss}			300		
Reverse Transfer Capacitance	C_{rss}			247		
Switching Parameters						
Total Gate Charge	Q_{g}	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 15\text{V}, I_{\text{D}} = 20\text{A}$		46.3		nC
Gate-Source Charge	Q_{gs}			8.8		
Gate-Drain Charge	Q_{gd}			9.2		
Reverse Recovery Charge	Q_{rr}	$I_{\text{F}} = 20\text{A}, dI/dt = 100\text{A/us}$		1.6		ns
Reverse Recovery Time	t_{rr}			11		
Turn-on Delay Time	$t_{\text{D(on)}}$			11		
Turn-on Rise Time	t_{r}	$V_{\text{GS}} = 10\text{V}, V_{\text{DD}} = 15\text{V}, R_{\text{L}} = 0.75\Omega, R_{\text{GEN}} = 3\Omega$		80		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			39		
Turn-off fall Time	t_{f}			92		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. $T_J = 25^\circ\text{C}$, $V_{\text{DD}} = 50\text{V}$, $V_{\text{G}} = 10\text{V}$, $R_{\text{G}} = 25\Omega$, $L = 0.5\text{mH}$, $I_{\text{AS}} = 20\text{A}$.
- C. P_d is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of $R_{\theta JA}$ is measured with the device mounted on the minimum recommend pad size, in the still air environment with $T_A = 25^\circ\text{C}$. The maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

**■ Typical Performance Characteristics****Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. On-Resistance vs. Drain Current and Gate Voltage****Figure 4. On-Resistance vs. Junction Temperature****Figure 5. Capacitance Characteristics****Figure 6. Gate Charge**



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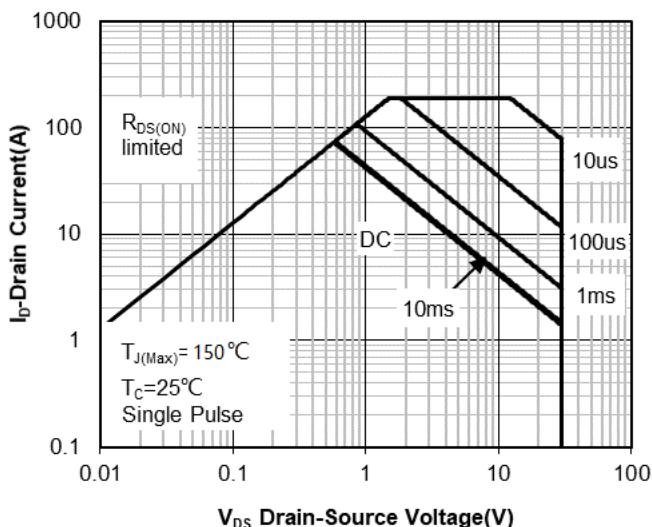


Figure 7. Safe Operation Area

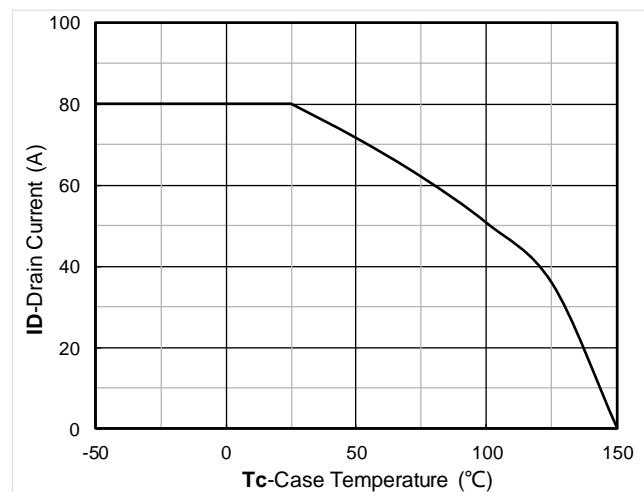


Figure 8. Maximum Continuous Drain Current vs Case Temperature

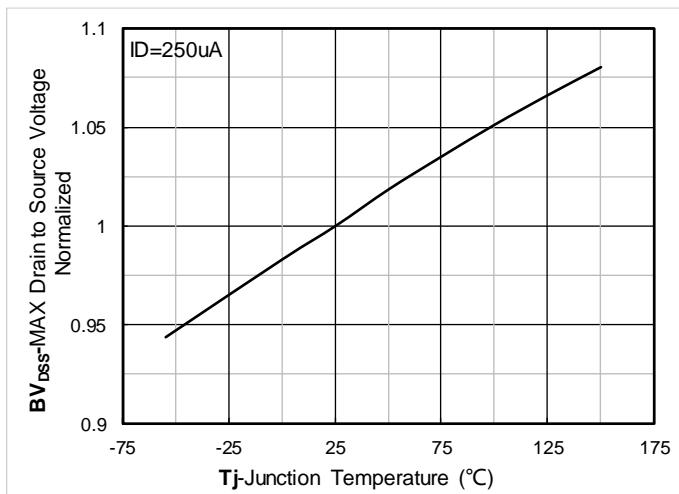


Figure 9. Normalized breakdown voltage

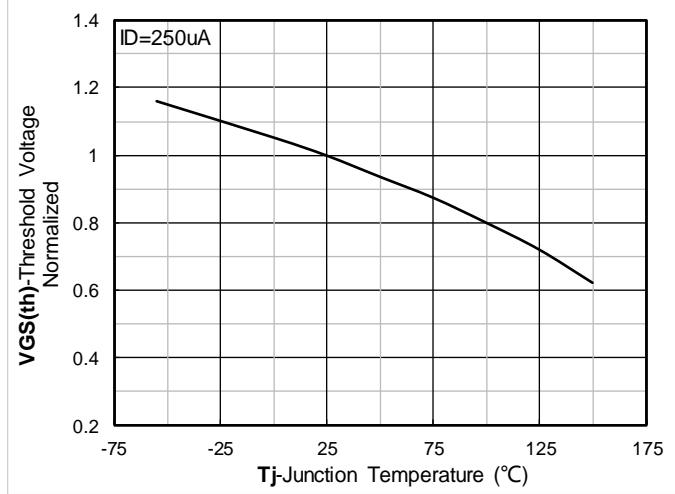


Figure 10. Normalized Threshold voltage

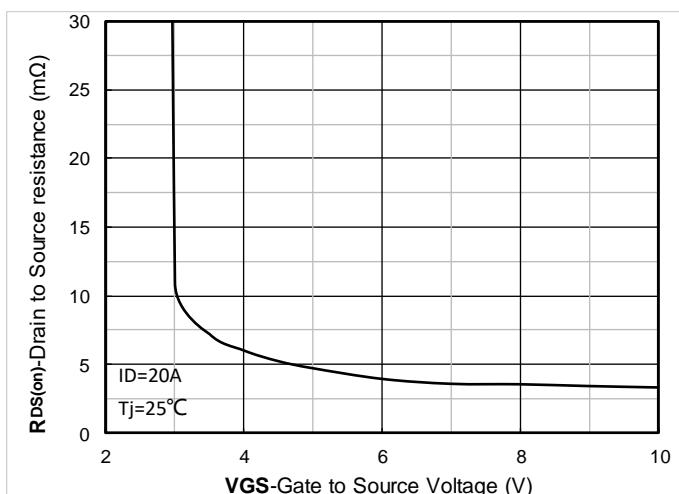


Figure 11. On-Resistance vs Gate to Source Voltage

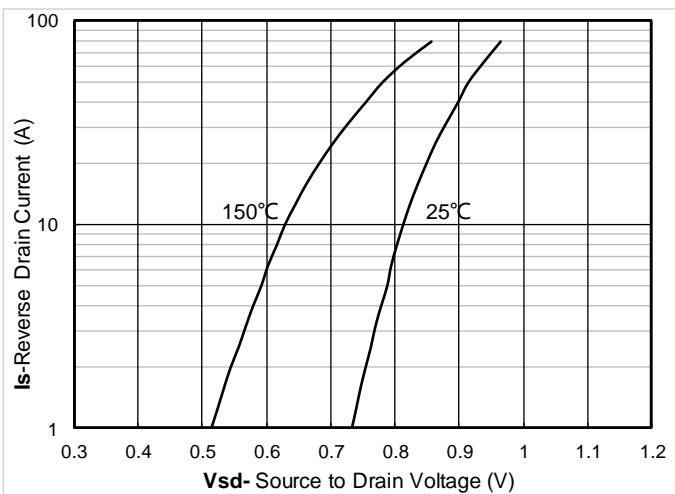


Figure 12. Forward characteristics of reverse diode

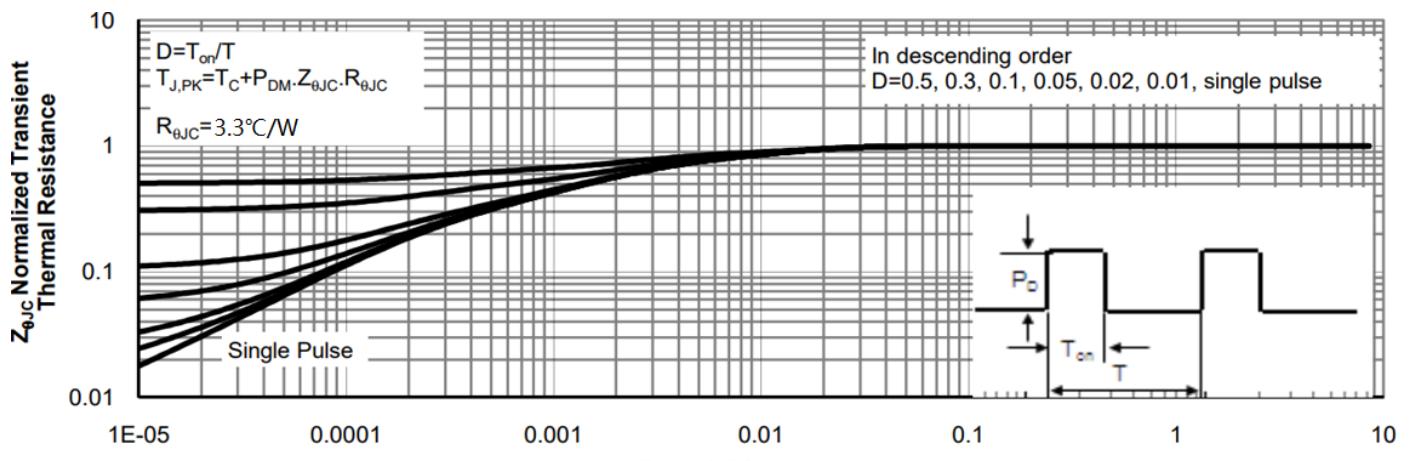
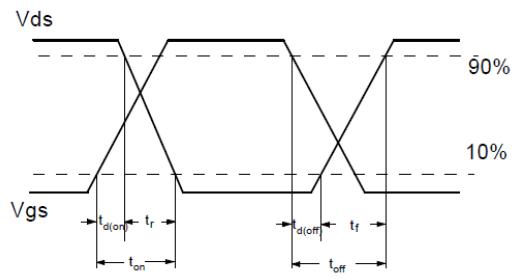
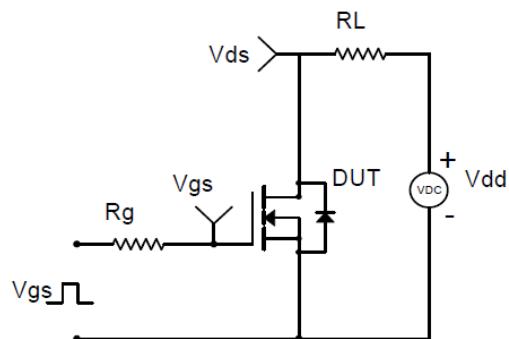
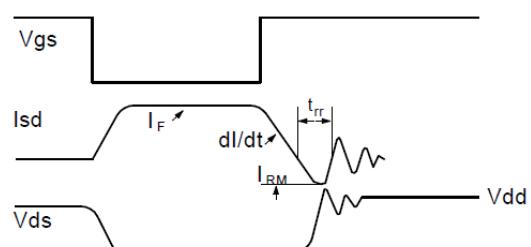
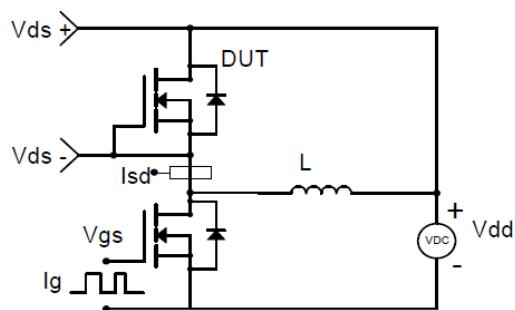


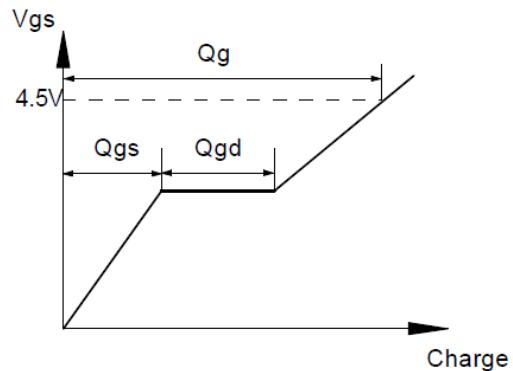
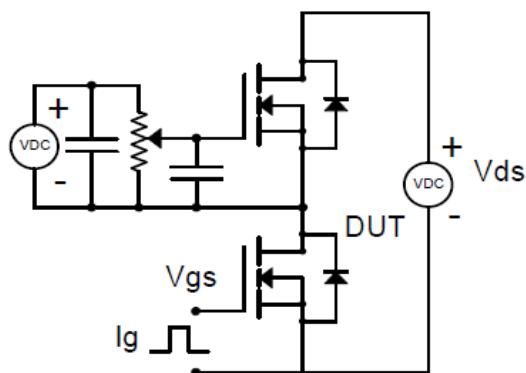
Figure 13. Normalized Maximum Transient Thermal Impedance



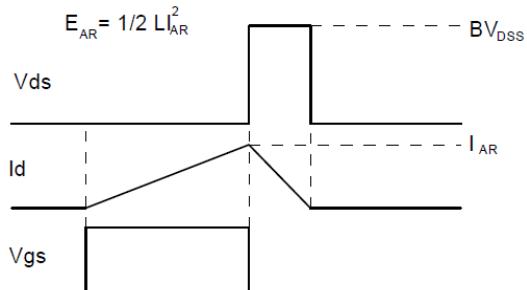
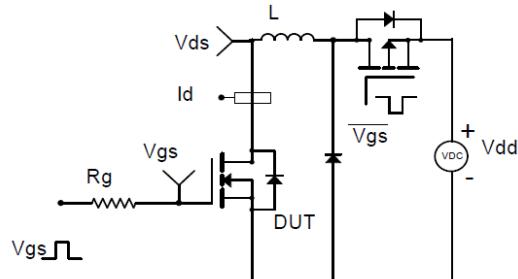
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



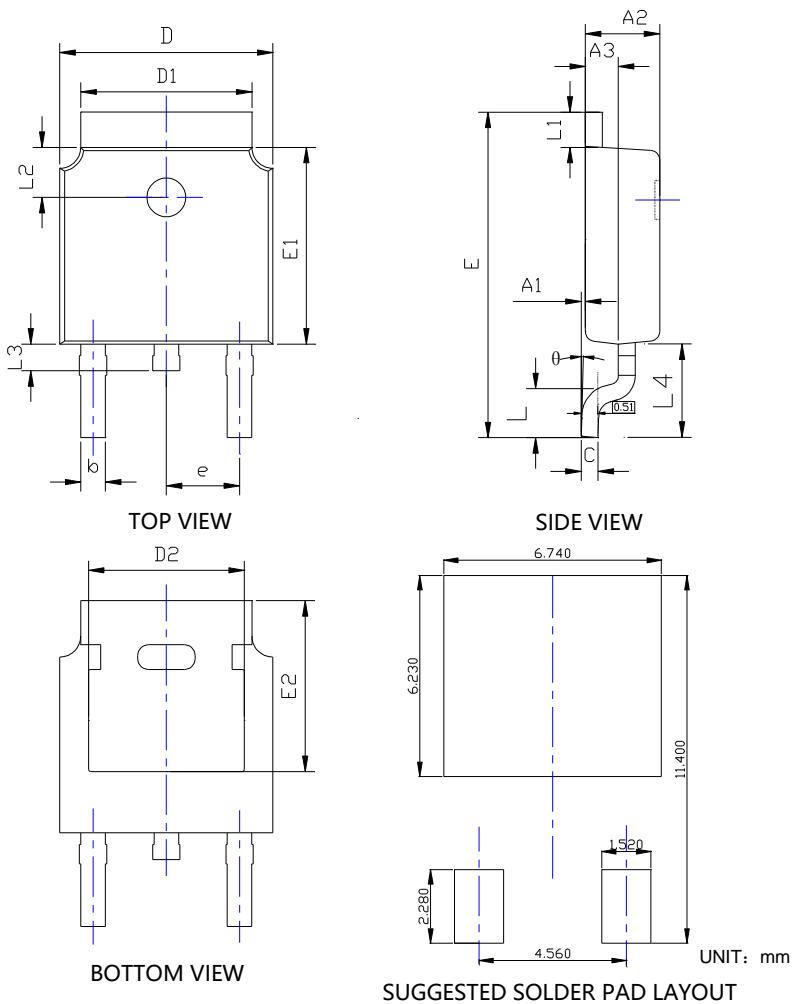
Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



■TO-252-B Package information



SYMBOL	DIMENSIONS			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A1	0.000	---	0.008	0.000	---	0.200
A2	0.087	0.091	0.094	2.200	2.300	2.400
A3	0.035	0.039	0.043	0.900	1.000	1.100
b	0.026	0.030	0.034	0.660	0.760	0.860
c	0.018	0.020	0.023	0.460	0.520	0.580
D	0.256	0.260	0.264	6.500	6.600	6.700
D1	0.203	0.209	0.215	5.150	5.300	5.450
D2	0.181	0.189	0.195	4.600	4.800	4.950
E	0.390	0.398	0.406	9.900	10.100	10.300
E1	0.236	0.240	0.244	6.000	6.100	6.200
E2	0.203	0.209	0.215	5.150	5.300	5.450
e	0.090BSC			2.286BSC		
L	0.049	0.059	0.069	1.250	1.500	1.750
L1	0.035	---	0.050	0.900	---	1.270
L2	0.055	---	0.075	1.400	---	1.900
L3	0.240	0.310	0.039	0.600	0.800	1.000
L4	0.114REF			2.900REF		
theta	0°	---	10°	0°	---	10°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



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